1N5711

General Purpose Axial Lead Glass Packaged Schottky Diodes

Rev. V3

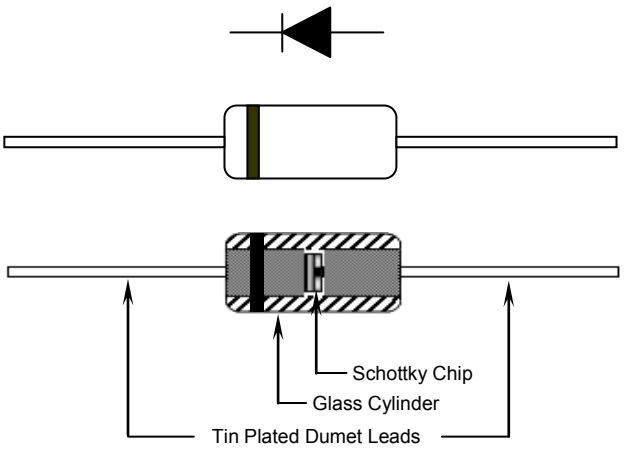
Features

- Low Leakage Current
- Pico Second Switching Speed
- Glass Hermetically Sealed Packages
- Offered in Tape & Reel Packaging
- RoHS* Compliant

Description and Applications

These silicon diodes are packaged in a hermetic axial lead glass package. Various uses include detecting, mixing and switching at low power levels. They are suitable for commercial switching along with control functions in narrow band receivers. These diodes can also be used in the UHF and VHF frequency bands for pulse shaping, sampling and as fast logic gates.

Glass Package Style (ODS-54)



Electrical Specifications[1]: T_A = +25°C

Parameter	Test Conditions	Units	Min.	Max.
Forward Voltage	1 mA 15 mA	V	—	0.41 1.00
Voltage Breakdown	10 µA	V	70	—
Leakage Current	50 V	nA	—	200
Total Capacitance	0 V, 1 MHz	pF	—	2.0

1. Effective minority carrier lifetime (TI) is 100 ps maximum measured with the Krakauer method at 5 mA.

Absolute Maximum Ratings[2,3]

Parameter	Absolute Maximum
Reverse Voltage	See voltage ratings
Power Dissipation	250 mW Derate linearly to 0 @ 135°C
Soldering Temperature	+230°C for 5 seconds 1 mm from glass
Operating Temperature	-65°C to +150°C
Storage Temperature	-65°C to +200°C

2. Exceeding any one or combination of these limits may cause permanent damage to this device.
3. MACOM does not recommend sustained operation near these survivability limits.

Ordering Information

Part Number	Package
1N5711	ESD Bag

* Restrictions on Hazardous Substances, European Union Directive 2011/65/EU.

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Assembly Recommendations

- Leads on axial leaded devices must be formed while being held firm. Bending the leads too close to the body of the part may cause internal damage to the device. Bends <0.060" from body are not recommended. Appropriate fixturing should be used.
- Devices may be soldered using standard 60/40, Sn/Pb or RoHS compliant solders. Axial leads are tin plated, 50 µM, thick to ensure an optimum connection.

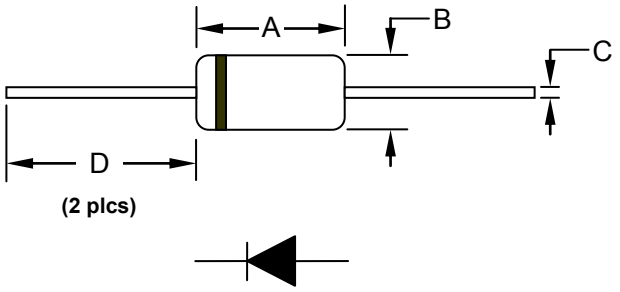
Handling Procedures

Please observe the following precautions to avoid damage:

Static Sensitivity

These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these HBM Class 0 devices.

Package Outline Dimensions



Dimension	Mils	mm
A	155 ± 10	3.94 ± 0.25
B	71 ± 3	1.8 ± 0.08
C	15 ± 1	0.38 ± 0.03
D (min.)	1000	25.4